

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Hitoshi MURATA	06/09/2011
Tetsuya KOSUGI	06/16/2011
<b>RECEIVING PARTY DATA</b>	
Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	13177306
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(215)568-6499
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	215-568-6400
Email:	AVenezia@vklaw.com
Correspondent Name:	Volpe and Koenig, P.C.
Address Line 1:	30 South 17th Street
Address Line 2:	United Plaza
Address Line 4:	Philadelphia, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI13-20910293US01 AV
NAME OF SUBMITTER:	Anthony L. Venezia
Total Attachments: 3 source=ExecutedAssignment_HITACHI13_20910293US01_EFS#page1.tif source=ExecutedAssignment_HITACHI13_20910293US01_EFS#page2.tif source=ExecutedAssignment_HITACHI13_20910293US01_EFS#page3.tif	

**CH \$40.00 13177306**

**ASSIGNMENT**

**MURATA, Hitoshi**, residing at 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, TOYAMA 9392393, Japan, a citizen of Japan; and **KOSUGI, Tetsuya**, residing at 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, TOYAMA 9392393, Japan, a citizen of Japan (hereafter jointly and severally referred to as the undersigned), are the inventors of

**SUBSTRATE PROCESSING APPARATUS AND HEATING EQUIPMENT**

for which the undersigned have executed an application for United States Letters Patent, U.S. Patent Application No. 13/177,306, filed July 6, 2011.

The undersigned hereby authorize assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

**HITACHI KOKUSAI ELECTRIC INC.**, a corporation, having a principal place of business at 14-1, Sotokanda 4-chome, Chiyoda-ku, TOKYO 1018980, Japan (hereafter referred to as the assignee), is desirous of acquiring the entire right, title and interest in said invention, all applications for and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, do hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of

the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrant that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 9th day of June, 2011

at Toyama-shi, Japan.

Witness:

Kohji Ogawa

H. Murata (L.S.)  
**MURATA, Hitoshi**

(Although not mandatory, if possible,  
please subscribe appropriate notarization and obtain APOSTILLE)

EXECUTED under seal on this 16th day of June, 2011

at Toyama-shi, Japan.

Witness:

Kohi Ogawa

J. Kosugi (L.S.)  
KOSUGI, Tetsuya

(Although not mandatory, if possible,  
please subscribe appropriate notarization and obtain APOSTILLE)